

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

1. (Currently amended) Flexible tube head (40, 40') formed of a plastic material, the head including an opening defined by an edge (41, 41') and a shoulder (42, 42') connecting the edge to the a flexible skirt of the a flexible tube, characterised in that it comprises, set in the mass of the plastic material forming the head, for packaging a product, the tube head comprising an electronic component (20, 20') intended to exchange, without electrical contact, information about the tube and/or its contents with a read or read/write device outside of the tube without any electrical contact, the electronic component being set within the plastic material forming the tube head such that there is no adhesive material in contact with the packaged product.
2. (Currently amended) Tube head according to claim 1 including a pivoting cap enabling formed of a plastic material for closing the opening to be closed and in which the electronic component is set in the mass of within the plastic material forming the cap.
3. (Currently amended) Tube head according to claim 1, in which the electronic component is placed at the level of the shoulder of the tube, in the mass of within the plastic material forming the head.
4. (Currently amended) Tube head according to any one of claims claim 1 to 3, in which the total thickness of the electronic component is less than 400 microns.
5. (Currently amended) Tube head according to any one of claims claim 1 to 4, in which the electronic component includes a support (21, 21') having a periphery, the periphery of the support (21, 21') of the component is enclosed by the plastic material forming the head.
6. (Currently amended) Tube head according to any one of claims claim 1 to 5, in which the support (21, 21') of the component consists at least partially of comprises a material that is melt-compatible with the plastic material forming the head.
7. (Original) Tube head according to claim 6, in which the support of the component is made of polyethylene or polypropylene.

8. (Currently amended) Tube head according to claim 6 or 7, in which the material that is melt-compatible with the plastic material of the head is an external layer that forms part of ~~the~~ an inner wall of the shoulder of the tube.

9. (Currently amended) Method for manufacturing ~~flexible tube heads a flexible tube head~~ characterized in that it uses an electronic component (20, 20') capable of exchanging, ~~without electrical contact~~, information with a read or read/write device, ~~typically an RFID-type electronic component, in that with no electrical contact comprising:~~ (a) depositing the electronic component ~~is placed inside the a cavity (17) of the a mold intended to form for forming~~ the head, ~~then in that the head is molded, wherein the electronic component being held inside the cavity of the mold for forming the head without use of adhesive material, and (b) molding the head, the plastic material flows flowing~~ so as to embed the electronic component, ~~thus making the assembly inseparable within the plastic material.~~

10. (Currently amended) Method ~~for manufacturing flexible tube heads~~ according to claim 9 in which the head is molded by injection ~~molded~~ molding.

11. (Canceled)

12. (Currently amended) Method ~~for manufacturing flexible tube heads~~ according to ~~any one of claims~~ claim 9 to 11, in which the electronic component is deposited on ~~the~~ a convex conical surface (11) of ~~the~~ a mandrel (10) of the mold, the mold being arranged such that the mandrel (10) is underneath the die (16).

13. (Currently amended) Method ~~for manufacturing flexible tube heads~~ according to ~~any one of claims~~ claim 9 to 12, in which the electronic component (20, 20') has a support (21, 21') comprising an external layer made of a plastic material that is melt-compatible with the plastic material of the head and in which the electronic component is deposited on the convex conical surface (11) of the head of the mandrel (10) ~~while having with~~ the external layer opposite the convex conical surface of the mandrel.

14. (Currently amended) Method ~~for manufacturing flexible tube heads~~ according to ~~any one of claims~~ claim 9 to 13, in which the electronic component (20') has a support in the

shape of a disk with a hole at its center and in that the electronic component is placed around the projection (14) of the mandrel used to shape ~~the inside of the~~ an inner surface of a neck.

15. (Currently amended) Flexible tube including a head and a flexible skirt, ~~characterised in that comprising the tube head of claim 1 comprises, set in the mass of the plastic material forming the head, preferably at the level of the shoulder, an electronic module capable of exchanging, without electrical contact, information on the tube and/or its contents with a read or read/write device, typically an RFID (Radio Frequency Identification) electronic component.~~

16. (Currently amended) Method for manufacturing a flexible tube provided with a head (40) and a skirt (30) in which the head is overmolded on ~~the~~ an end (31) of the skirt, ~~wherein comprising (a) fitting the skirt is fitted around the a mandrel of the a mold, driven and (b) operating the mold so that an~~ the end (31) of the skirt overflows and is contained in ~~the~~ the mold cavity (17) delimited by ~~the head a head (11) of the a mandrel (10) and the a cavity of the a die (16), characterized in that an electronic component (20), capable of for~~ exchanging, without electrical contact, information with a read or read/write device, ~~typically an RFID type electronic component, is deposited on the head (11) of the mandrel (10) in contact with the end (31) of the skirt (30) that overflows into the mold cavity (17).~~

17. (New) Tube head according to claim 1 in which the electronic component is an RFID-type electronic component.

18. (New) Method according to claim 9 in which the electronic component is an RFID-type electronic component.

19. (New) Method according to claim 16 in which the electronic component is an RFID-type electronic component.